## ABSTRACT

Embodiments of the present disclosure provide a semiconductor structure, including: a substrate, where the substrate is covered with a dielectric layer, and the dielectric layer includes a first region and a second region that surrounds the first region; a first conductive pad disposed in the dielectric layer of the first region, where a top surface of the first conductive pad has a recessed or protruded part, and the dielectric layer covers the top surface of the first conductive pad; and a first bonding pad disposed in the dielectric layer of the second region, where the first bonding pad is disposed around the first conductive pad, the first bonding pad has a top surface exposed to the dielectric layer, and a bottom surface of the first bonding pad is higher than the top surface of the first conductive pad.

[FIG. 1A]